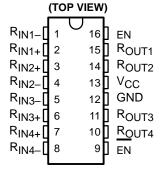
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- >400 Mbps (200 MHz) Signaling Rates
- Flow-Through Pinout Simplifies PCB Layout
- 50 ps Channel-to-Channel Skew (Typ)
- 200 ps Differential Skew (Typ)
- Propagation Delay Times 2.7 ns (Typ)
- 3.3-V Power Supply Design
- High Impedance LVDS Inputs on Power Down
- Low-Power Dissipation (40 mW at 3.3 V Static)
- Accepts Small Swing (350 mV) Differential Signal Levels
- Supports Open, Short, and Terminated Input Fail-Safe
- Industrial Operating Temperature Range (-40°C to 85°C)
- Conforms to TIA/EIA-644 LVDS Standard
- Available in SOIC and TSSOP Packages
- Pin-Compatible With DS90LV048A From National

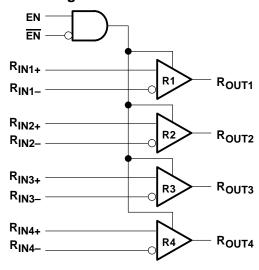
description

The SN65LVDS048A is a quad differential line receiver that implements the electrical characteristics of low-voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5-V differential standard levels (such as EIA/TIA-422B) to reduce the power, increase the switching speeds, and allow operation with a 3.3-V supply rail. Any of the quad

SN65LVDS048AD (Marked as LVDS048A) SN65LVDS048APW (Marked as DL048A)



functional diagram



differential receivers will provide a valid logical output state with a ± 100 -mV differential input voltage within the input common-mode voltage range. The input common-mode voltage range allows 1 V of ground potential difference between two LVDS nodes.

The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100 Ω . The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other system characteristics.

The SN65LVDS048A is characterized for operation from -40°C to 85°C.



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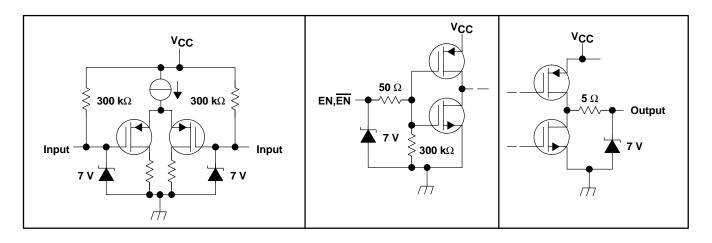


TRUTH TABLE

DIFFERENTIAL INPUT	ENABLES		OUTPUT
R _{IN+} – R _{IN}	EN EN		ROUT
V _{ID} ≥ 100 mV			Н
$V_{ID} \le -100 \text{ mV}$	Н	L or OPEN	L
Open/short or terminated			Н
Х	All othe	Z	

H = high level, L = low level, X = irrelevant, Z = high impedance (off)

equivalent input and output schematic diagrams



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range (V _{CC)}	0.3 V to 4 V
Input voltage range, $V_I(R_{IN+}, R_{IN-})$	0.3 V to 4 V
Enable input voltage (EN, EN)	0.3 V to (V _{CC} +0.3 V)
Output voltage, V _O (R _{OUT})	0.3 V to (V _{CC} +0.3 V)
Bus-pin (R _{IN+} , R _{IN-}) Electrostatic discharge (see Note 2)	> 10 kV
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
 - 2. Tested in accordance with MIL-STD-883C Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	OPERATING FACTOR [‡] ABOVE T _A = 25°C	T _A = 85°C POWER RATING
D	950 mW	7.6 mW/°C	494 mW
PW	774 mW	6.2 mW/°C	402 mW

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.



recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	3	3.3	3.6	V
Receiver input voltage	GND		3	V
Common-mode input voltage, V _{IC}	V _{ID} 2	2	$2.4 - \frac{ V_{\text{ID}} }{2}$	V
			V _{CC} – 0.8	
Operating free-air temperature, T _A	-40	25	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Note 3)

PARAMETER		TEST CO	TEST CONDITIONS		TYP [†]	MAX	UNIT
V _{IT+}	Differential input high threshold voltage	V _{CM} = 1.2 V, 0.05 V, 2.35 V				100	
V_{IT-}	Differential input low threshold voltage	(see Note 4)					mV
V(CMR)	Common mode voltage range	V _{ID} = 200 mV pk to p	k (see Note 5)	0.1		2.3	V
		V _{IN} = 2.8 V	.,	-20	±1	20	μΑ
I _{IN}	Input current	$V_{IN} = 0 V$	$V_{CC} = 3.6 \text{ V or } 0 \text{ V}$	-20	±1	20	μΑ
		V _{IN} = 3.6 V	VCC = 0 V	-20	±1	20	μΑ
		$I_{OH} = -0.4 \text{ mA}, V_{ID} =$	= 200 mV	2.7	3.2		V
VOH Output high volta	Output high voltage	I _{OH} = -0.4 mA, input terminated		2.7	3.2		V
		I _{OH} = -0.4 mA, input shorted		2.7	3.2		V
V _{OL}	Output low voltage	$I_{OL} = 2 \text{ mA}, V_{ID} = -200 \text{ mV}$			0.05	0.25	V
los	Output short circuit current	Enabled, V _{OUT} = 0 V (see Note 6)			-65	-100	mA
I _{O(Z)}	Output 3-state current	Disabled, VOUT = 0 V or VCC		-1		1	μΑ
VIH	Input high voltage			2.0		VCC	V
V _{IL}	Input low voltage					0.8	V
l _l	Input current (enables)	$V_{IN} = 0 \text{ V or } V_{CC},$ Other input = V_{CC} or GND		-10		10	μΑ
VIK	Input clamp voltage	I _{CL} = -18 mA		-1.5	-0.8		V
Icc	No load supply current, receivers enabled	EN = V _{CC} , Inputs open			8	15	mA
I _{CC} (Z)	No load supply current, receivers disabled	EN = GND, Inputs open			0.6	1.5	mA

[†] All typical values are at 25°C and with a 3.3-V supply.

NOTES: 3. Current into device pin is defined as positive. Current out of the device is defined as negative. All voltages are referenced to ground, unless otherwise specified.

- 4. V_{CC} is always higher than R_{IN+} and R_{IN-} voltage, R_{IN-} and R_{IN+} have a voltage range of $-0.2\,\text{V}$ to $V_{CC}-V_{ID}/2$. To be compliant with ac specifications the common voltage range is 0.1 V to 2.3 V.
- 5. The VCMR range is reduced for larger V_{ID} , Example: If $V_{ID} = 400$ mV, the VCMR is 0.2 V to 2.2 V. The fail-safe condition with inputs shorted is not supported over the common-mode range of 0 V to 2.4 V, but is supported only with inputs shorted and no external common-mode voltage applied. A V_{ID} up to V_{CC} -0 V may be applied to the R_{IN+} and R_{IN-} inputs with the common-mode voltage set to V_{CC} /2. Propagation delay and differential pulse skew decrease when V_{ID} is increased from 200 mV to 400 mV. Skew specifications apply for 200 mV < V_{ID} < 800 mV over the common-mode range.
- 6. Output short circuit current (Ios) is specified as magnitude only, minus sign indicates direction only. Only one output should be shorted at a time. Do not exceed maximum junction temperature specification.



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switching characteristics over recommended operating conditions (unless otherwise noted) (see Notes 7)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
^t PHL	Differential propagation delay, high-to-low		1.9	2.7	3.7	ns
^t PLH	Differential propagation delay, low-to-high		1.9	2.9	3.7	ns
tSK(p)	Differential pulse skew (tpHLD – tpLHD) (see Note 8)			200	450	ps
tSK(o)	Differential channel-to-channel skew; same device (see Note 8)	C _L = 15 pF		50	500	ps
tSK(pp)	Differential part-to-part skew (see Note 10)	V _{ID} = 200 mV (see Figure 1 and 2)			1	ns
tSK(lim)	Differential part-to-part skew (see Note11)	(**************************************			1.5	ns
t _r	Rise time			0.5	1	ns
t _f	Fall time			0.5	1	ns
^t PHZ	Disable time high to Z			8	9	ns
^t PLZ	Disable time low to Z	R _L = 2 K Ω		6	8	ns
^t PZH	Enable time Z to high	C _L = 15 pF (see Figure 3 and 4)		8	10	ns
tPZL	Enable time Z to low			7	8	ns
f(MAX)	Maximum operating frequency (see Note 12)	All channels switching	200	250		MHz

[†] All typical values are at 25°C and with a 3.3-V supply.

- NOTES: 7. Generator waveform for all tests unless otherwise specified: f = 1 MHz, $Z_O = 50 \Omega$, tr and tf $(0\% 100\%) \le 3 \text{ ns for R}_{IN}$.
 - 8. $t_{SK(p)}|t_{PLH} t_{PHL}|$ is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.
 - 9. $t_{SK(0)}$ is the differential channel-to-channel skew of any event on the same device.
 - 10. tsK(pp) is the differential part-to-part skew, and is defined as the difference between the minimum and the maximum specified differential propagation delays. This specification applies to devices at the same VCC and within 5°C of each other within the operating temperature range.
 - 11. t_{sk(lim)} part-to-part skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices over recommended operating temperature and voltage ranges, and across process distribution. t_{sk(lim)} is defined as |Min Max| differential propagation delay.
 - 12. $f_{\text{(MAX)}}$ generator input conditions: $f_{\text{r}} = t_{\text{f}} < 1 \text{ ns (0\% to 100\%)}$, 50% duty cycle, 0 V to 3 V. Output criteria: duty cycle = 45% to 55%, $V_{\text{OD}} > 250 \text{ mV}$, all channels switching



PARAMETER MEASUREMENT INFORMATION

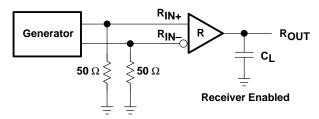


Figure 1. Receiver Propagation Delay and Transition Time Test Circuit

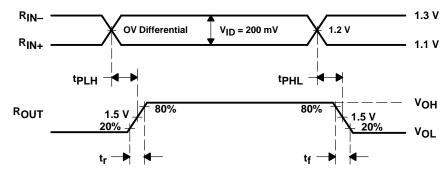
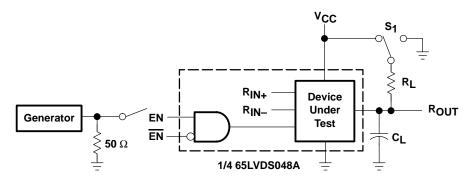


Figure 2. Receiver Propagation Delay and Transition Time Waveforms

PARAMETER MEASUREMENT INFORMATION



 C_L Includes Load and Test Jig Capacitance. $S_1 = V_{CC}$ for tpzL and tpLz Measurements.

 $S_1 = GND$ for tpzH and tpHZ Measurements.

Figure 3. Receiver 3-State Delay Test Circuit

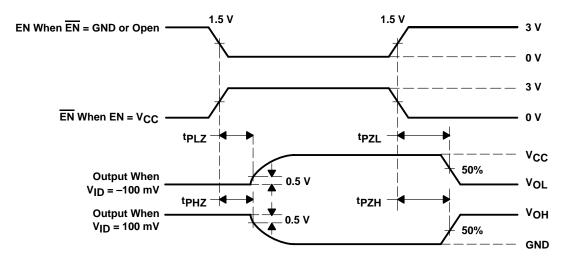
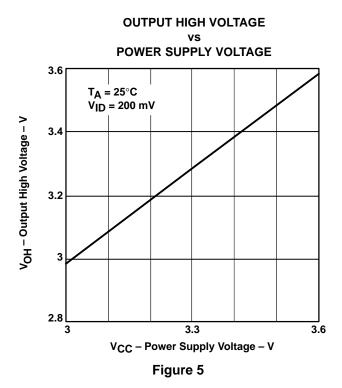
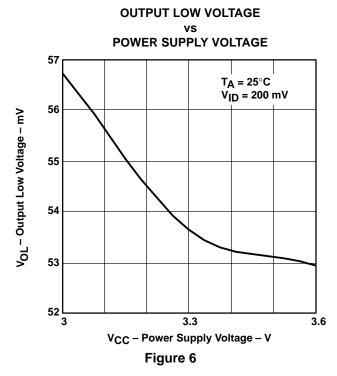
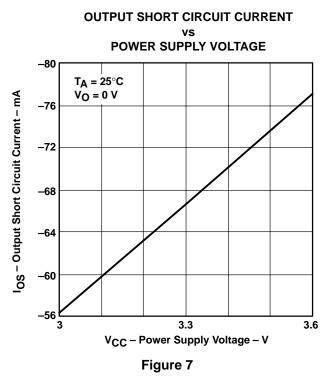


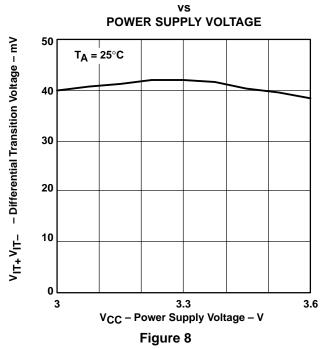
Figure 4. Receiver 3-State Delay Waveforms

TYPICAL CHARACTERISTICS









DIFFERENTIAL TRANSITION VOLTAGE

TYPICAL CHARACTERISTICS

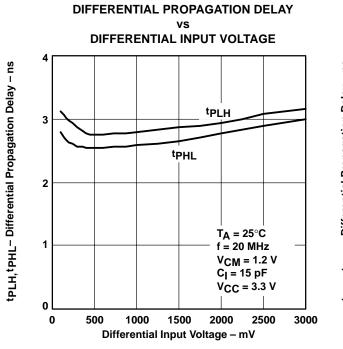


Figure 9

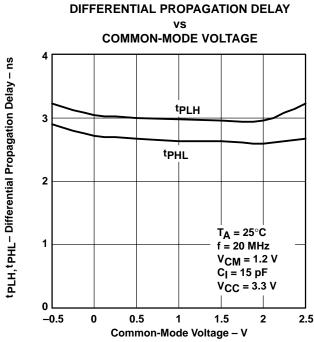


Figure 10

DATA TRANSFER RATE FREE-AIR TEMPERATURE 800 750 Data Transfer Rate - Mxfr/s 700 650 600 2¹⁵ -1 prbs NRZ $V_{CC} = 3.3 V$ 550 $V_{ID} = 0.4 V$ V_{IC} = 1.2 V C_L = 5.5 pF 500 40% Open Eye 450 4 Receivers Switching Input Jitter < 45 ps 400 -20 0 20 40 80 -40 60 T_A - Free-Air Temperature - °C Figure 11

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APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. Tl's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 10. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

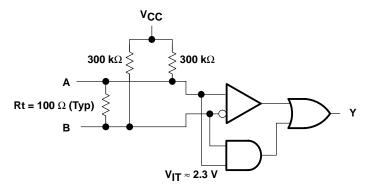


Figure 12. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

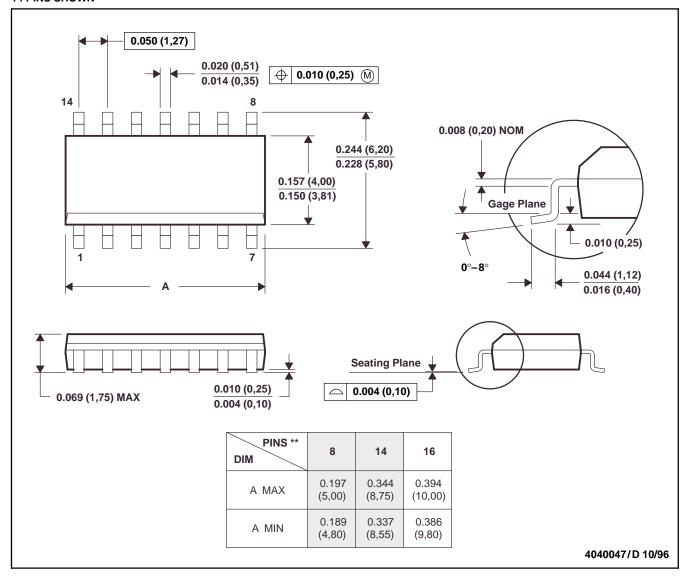
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MECHANICAL DATA

D (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

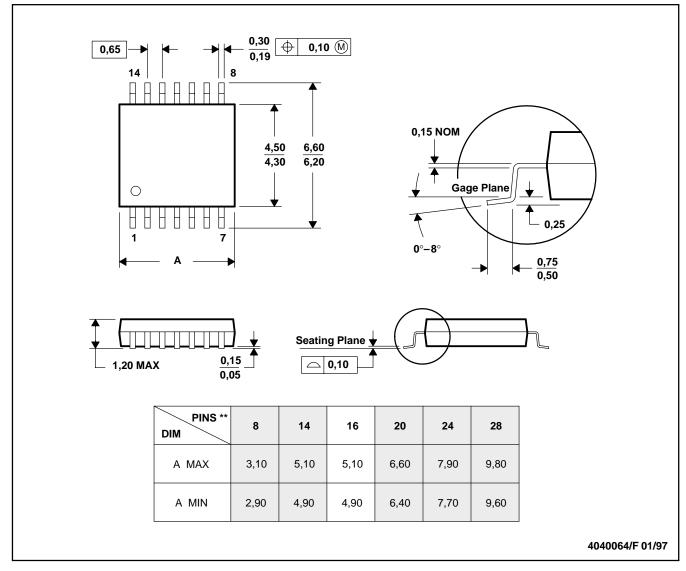
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MECHANICAL DATA

PW (R-PDSO-G**)

14 PINS SHOWN

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D. Falls within JEDEC MO-153



PACKAGE OPTION ADDENDUM

4-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LVDS048AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDS048ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDS048APW	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LVDS048APWR	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM

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NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

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OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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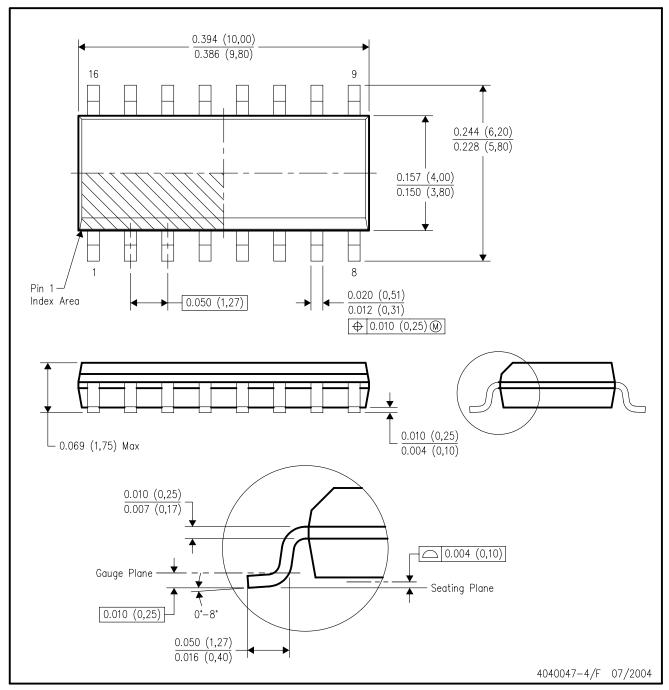
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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D (R-PDSO-G16)

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PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



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D. Falls within JEDEC MO-153

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